

Amendments to the Claims:

Please cancel claim 14 and amend claims 1, 4-7 and 9-12 as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended). A sample assembly for a thermoelectric analyzer comprising:

- (a) an electrically-insulating substrate having a longitudinally-central region and two longitudinally-end regions;
- 5 (b) an adhesive layer disposed on said longitudinally-central region and made of a material selected from a group consisting of indium and gold-tin alloy a pair of junction electrode layers non-contiguously formed on said substrate;
- (c) a pair of junction electrode layers formed on said two longitudinally-end regions respectively with certain distances from an adhesive layer disposed on said substrate, said adhesive layer being non-contiguous with said pair of junction electrode layers;
- 10 (d) a sample fixed to said adhesive layer, said sample and being non-contiguous with said pair of junction electrode layers

for thermostatic analysis in which an electric property of said sample is measured as a temperature of said sample varies;

(e) a pair of electrode layers formed on a top surface of said sample; and

20 (f) ~~two electrically conductive wires,~~ a first electrically-conductive wire connecting one of said electrode layers with one of said junction electrode layers; and

25 (g) a second electrically-conductive wire connecting the other of said electrode layers with the other of said junction electrode layers wherein an electrical property of the sample is measured as a temperature of the sample varies.

Claim 2 (Original). A sample assembly according to claim 1, wherein said adhesive layer is made of indium.

Claim 3 (Original). A sample assembly according to claim 2, wherein said substrate is made of a material selected from a group consisting of aluminum nitride, boron nitride, beryllium oxide and aluminum oxide.

Claim 4 (Currently Amended). A sample assembly according to claim 3, wherein each of said ~~pair of~~ electrode layers and said

pair of junction electrode layers is made of a multilayer including a top layer which is a gold layer, and said first and 5 second electrically-conductive wires are gold wires.

Claim 5 (Currently Amended). A sample assembly according to claim 4, wherein said pair of electrode layers, said pair of junction electrode layers and said first and second electrically-conductive wire means wires are arranged mirror-symmetrical with respect to a center of said sample.

Claim 6 (Currently Amended). A sample assembly according to claim 5, wherein said sample is a compound semiconductor.

Claim 7 (Currently Amended). A sample assembly according to claim 1, wherein said adhesive layer is made of a gold-tin alloy.

Claim 8 (Original). A sample assembly according to claim 1, wherein said substrate is made of a material selected from a group consisting of aluminum nitride, boron nitride, beryllium oxide and aluminum oxide.

Claim 9 (Currently Amended). A sample assembly according to claim 1, wherein said sample assembly is adapted to be supported

by two support rods which also serve also as conductors for an electric circuit, and wherein gold washers are inserted between 5 said support rods and said junction electrode layers.

Claim 10 (Currently Amended). A sample assembly according to claim 1, wherein each of said electrode layers and said junction electrode layers is ~~made of~~ a multilayer including a top layer which is a gold layer, and said first and second electrically-conductive wire means wires are gold wires.

Claim 11 (Currently Amended). A sample assembly according to claim 1, wherein said pair of electrode layers, said pair of junction electrode layers and said first and second electrically-conductive wires ~~wire means~~ are arranged mirror-symmetrical with respect to a center of said sample.

Claim 12 (Currently Amended). A sample assembly according to claim 1, wherein said sample is a compound semiconductor.

Claim 13 (Original). A sample assembly according to claim 1, wherein said sample has a plane size of 5 mm x 5 mm or less.

Claim 14 (Cancelled).

Amendments to the Drawings:

The attached sheets of drawings include changes to Fig. 5. Specifically, attached hereto is an annotated sheet showing changes to Fig. 5 and a replacement sheet for Fig. 5 which includes the changes thereto. The changes to Fig. 5 are directed to a portion which was previously not translated from Japanese into English at the time the present application was filed. The amendment of Fig. 5 is supported by the application as originally filed (see page 15, lines 17-21 of the present application).

Attachments: Marked sheet showing changes to Fig. 5

Replacement sheet for Fig. 5